



**PATENT**

**POWER OF ATTORNEY TO PROSECUTE APPLICATIONS BEFORE THE USPTO**

I hereby revoke all previous powers of attorney given in the application in the attached statement under 37 C.F.R. § 3.73(b).

I hereby grant power of attorney to FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P. Customer Number 22,852, as attorneys or agents to represent the undersigned before the United States Patent and Trademark Office in connection with any and all patent applications assigned only to the undersigned according to the USPTO assignment records or assignment documents attached to this form in accordance with 37 C.F.R. § 3.73(b).

Please also send all future correspondence concerning the application identified in the attached statement under 37 C.F.R. § 3.73(b) to Finnegan, Henderson, Farabow, Garrett & Dunner, L.L.P., Customer Number 22,852.

The undersigned understands that a copy of this form, together with a statement under 37 C.F.R. § 3.73(b) is required to be filed in each application in which this form is used. The statement under 37 C.F.R. § 3.73(b) may be completed by one of the practitioners appointed in this form, if the appointed practitioner is authorized to act on behalf of the assignee, and must identify the application in which the Power of Attorney is to be filed.

The individual whose signature and title is supplied below is authorized to act on behalf of the assignee.

Date: July 27, 2005

Name: Koichi Wada

Title: Manager, Intellectual Property Division

Signature: Koichi Wada

## ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

## COMMUNICATION METHOD, COMMUNICATION SYSTEM AND COMMUNICATION DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP03/07135, International Filing Date: 5 June 2003.

This assignment executed on the dates indicated below.

Takashi SASAI

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

October 4, 2004

Date of this assignment

Hiroshi KAKUDA

Name of second inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor

October 4, 2004

Date of this assignment

Kazuya ODAGIRI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

October 4, 2004

Date of this assignment

Koji NISHIMURA

Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fourth inventor

*Koji Nishimura*

*October 31, 2004*

Signature of fourth inventor

Date of this assignment